

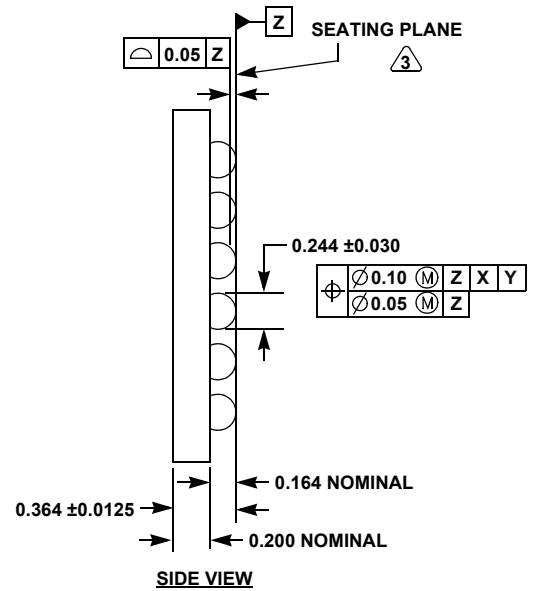
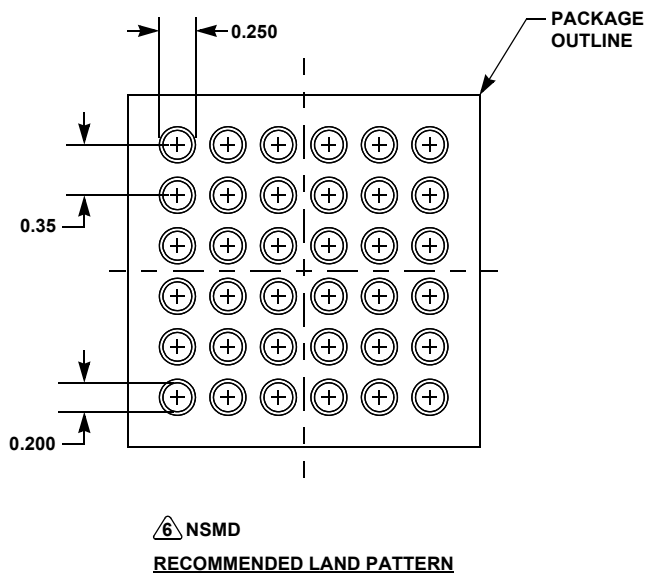
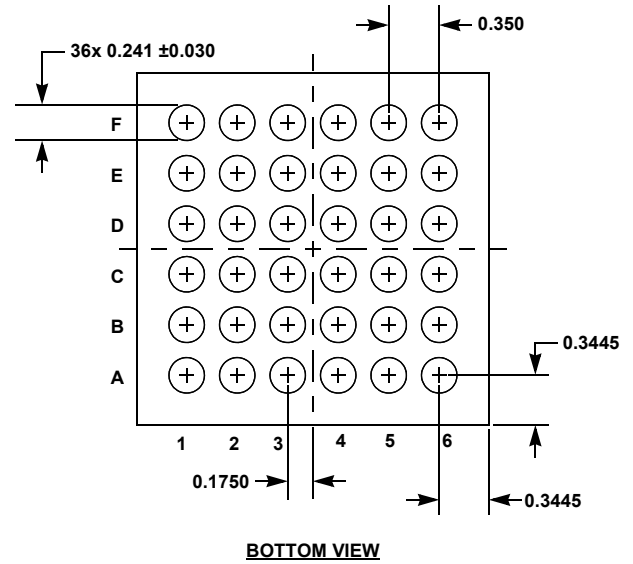
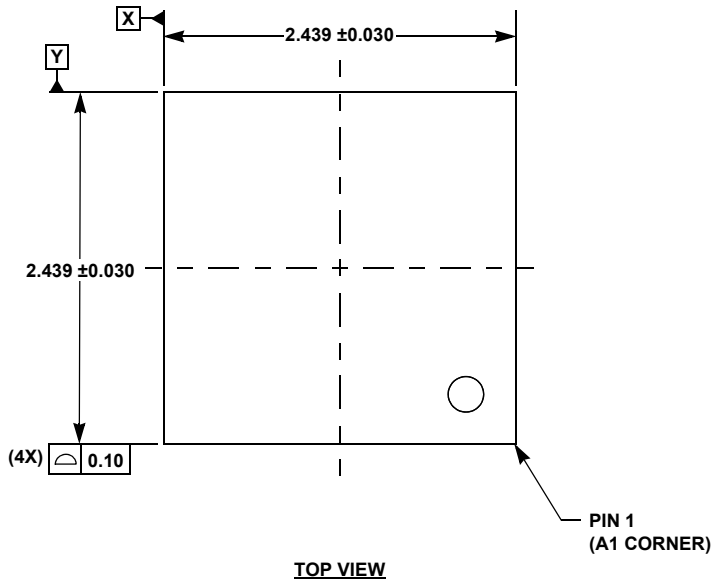
Plastic Packages for Integrated Circuits

Package Outline Drawing

W6x6.36B

36 Ball Wafer Level Chip Scale Package (WLCSP 0.35mm Pitch)

Rev 0, 1/16



NOTES:

1. All dimensions are in millimeters.
2. Dimensions and tolerance per ASMEY 14.5-1994.
3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. Dimension is measured at the maximum bump diameter parallel to primary datum Z .
5. Bump position designation per JESD 95-1, SPP-010.
6. NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).